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## **Closed Topic Search**

Published on SBIR.gov (https://www.sbir.gov)

 DMEA13B-001: Electrochemical Micro-Capacitors Utilizing Carbon Nanostructures

Release Date: 07-26-2013Open Date: 08-26-2013Due Date: 09-25-2013Close Date: 09-25-2013

TECHNOLOGY AREAS: Materials/Processes, Electronics The technology within this topic is restricted under the International Traffic in Arms Regulation (ITAR), which controls the export and import of defense-related material and services. Offerors must disclose any proposed use of foreign nationals, their country of origin, and what tasks each would accomplish in the statement of work in accordan ...

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## 2. <u>DMEA122-001: High Speed, High Resolution X-ray System for Inspecting Integrated Circuits</u>

Release Date: 04-24-2012Open Date: 05-24-2012Due Date: 06-27-2012Close Date: 06-27-2012

OBJECTIVE: Develop an affordable x-ray microscope system for use in performing integrated circuit (IC) reverse engineering. DESCRIPTION: X-ray microscopy using a synchrotron as the x-ray source has been demonstrated to be an extremely valuable tool in the performance of high throughput integrated circuit evaluation and reverse engineering efforts. However, synchrotron x-ray sources are prohi ...

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## **3.** <u>DMEA15B-001: Optimized Scintillator for High Resolution X-ray Imaging at</u> 9keV

Release Date: 04-24-2015Open Date: 05-26-2015Due Date: 06-24-2015Close Date: 06-24-2015

Rapid Integrated Circuit (IC) inspection using x-ray microscopy requires novel x-ray scintillating materials with high efficiency and high spatial resolution. Current scintillator materials, such as Cesium Iodide (CsI), suffer from a trade-off between efficiency and spatial resolution. Novel materials with higher stopping power and light yields are necessary to address the stringent requirements o ...

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